Technical Visit to Inari Technology Sdn Bhd

By

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On Monday, 27 April 2026, the Electronic Engineering Technical Division (eETD) of IEM successfully organised a technical visit to Inari Technology Sdn Bhd, located at Bayan Lepas, Penang. The visit attracted 25 participants from various engineering backgrounds with the objective of enhancing their understanding of semiconductor assembly, packaging, testing technologies, and advanced manufacturing practices that support Industry 4.0 development in the global semiconductor industry.

The technical visit also provided participants with valuable exposure to the latest trends and market outlook within the semiconductor sector, particularly in relation to the rapid expansion of artificial intelligence (AI), data centres, automotive electronics, and communication technologies. Through this program, participants gained deeper insight into the operational capabilities, manufacturing ecosystem, and technological innovations implemented by Inari Technology in supporting global semiconductor supply chains.

Technical Briefing

The visit commenced with a warm welcome and registration session, followed by an introductory briefing conducted by the Inari Technology management team. Participants were introduced to the company's background, core business operations, and its role as one of the leading Outsourced Semiconductor Assembly and Test (OSAT) service providers in Malaysia as in figure 1. The briefing highlighted Inari's involvement in semiconductor packaging, wafer probing, RF testing, system-in-package (SiP) assembly, and advanced electronic manufacturing solutions that support global technology companies.

Figure 1: Technical presentation by Mr Noorazidi Che Azib, VP Operation Technology & Strategic Programs of Inari Technology Sdn Bhd.

During the presentation session, the speakers shared valuable insights into the current outlook of the global semiconductor industry. Participants were informed that semiconductor device revenue is projected to continue growing significantly, driven by increasing demand from mobile devices, automotive electronics, industrial automation, servers, artificial intelligence applications, and telecommunication infrastructure as figure 2. The presentation highlighted that the semiconductor industry is expected to exceed USD 750 billion by 2028 and potentially reach USD 1 trillion beyond 2030, demonstrating the strategic importance of semiconductor technologies in future economic growth.

Figure 2: Mr Noorazidi explaining the current semiconductor industry outlook in Malaysia

In addition, the briefing emphasized the unprecedented global expansion of semiconductor fabrication facilities (fabs), particularly 300 mm wafer fabs, across regions such as China, Taiwan, the United States, Europe, Korea, Japan, and Southeast Asia. Participants learned how increasing investments in semiconductor fabrication and advanced packaging technologies are reshaping the global electronics ecosystem and creating strong demand for skilled engineering talent and innovative manufacturing solutions.

The speakers also explained the importance of advanced packaging and testing processes in ensuring product reliability, high performance, and miniaturization of modern electronic devices. Particular attention was given to radio frequency (RF) filters, fibre-optic transceivers, sensors, and integrated circuit technologies that support next-generation communication systems, automotive electronics, and AI-driven applications. The session provided participants with a clearer understanding of how semiconductor manufacturing integrates precision engineering, automation, quality assurance, and high-volume production to meet strict global standards.

Facility Tour

Following the technical briefing, participants were taken on a guided tour of Inari Technology's production facilities. The tour offered first-hand exposure to testing operations within a high-technology manufacturing environment. The engineering team demonstrated the implementation of automation systems and smart manufacturing technologies throughout the production line. Participants observed how automated equipment and vision inspection systems are integrated to improve production efficiency, reduce manufacturing defects, and maintain product consistency as figure 3.

Figure 3: The participants were exposed to one of the production line

During the visit, participants had the opportunity to interact directly with Inari engineers and technical personnel, who shared practical insights into manufacturing challenges, process optimization, and emerging trends within the semiconductor industry. The engagement session enabled participants to better appreciate the multidisciplinary knowledge required in modern semiconductor manufacturing, encompassing electronics, automation, software systems, data analysis, and precision mechanical engineering.

Conclusion

The technical visit to Inari Technology Sdn Bhd was highly informative and beneficial for all participants. The program successfully provided valuable industrial exposure to advanced semiconductor assembly, testing technologies, automation systems, and current global semiconductor market trends. Participants gained deeper insight into the rapidly evolving semiconductor ecosystem and the critical role played by Malaysian industries in supporting global electronics manufacturing and innovation. The session concluded with a souvenir presentation by representatives from IEM eETD and a group photo as in figure 4 and figure 5.

Figure 4: Souvenir presentation by representatives from IEM eETD to Inari Technology Sdn Bhd

Figure 5: Group photo with the participants